

REV	MODIFICATION	DATE	DRAW
D	EN-13-1105	2013.11.14	EvanTeng
E	ECN2-0000019	2013.12.03	EvanTeng
F	ECN2-00000181	2014.12.02	Stacy

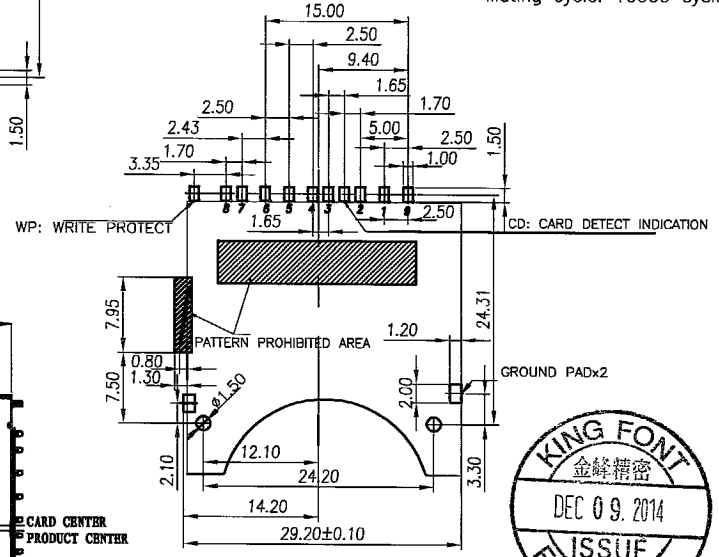
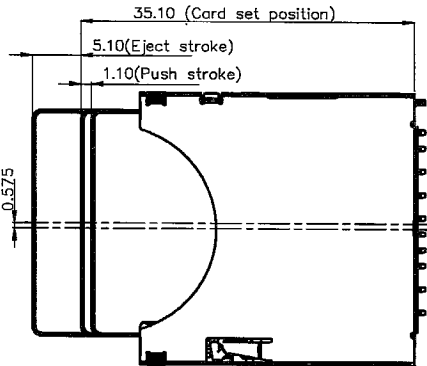
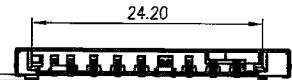
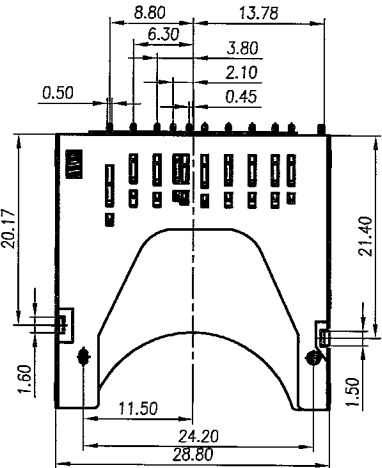
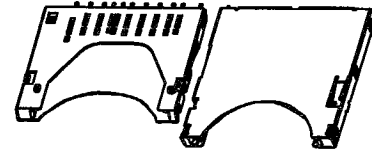
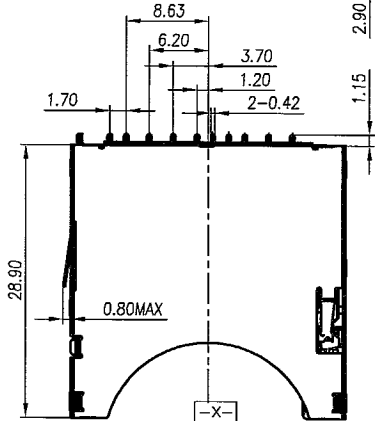
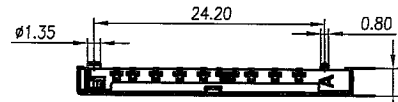
**SPECIFICATION**

**1. Material:**

Insulator: LCP, rated UL94V-0, color: black.  
 Contacts; Phosphor Bronze,  
 Tin 160u" at Solder Tail,  
 Selected Gold on Contact Area Plating.  
 Ground: Phosphor Bronze, Tin 160u".  
 Shell: Stainless.

**2. Electrical Characteristics:**

Operating voltage : 50V(AC/DC).  
 Current rating : 0.5 A.  
 Operating Temperature: -25°C~+90°C.  
 Insulation resistance: 1000M ohms min. at 500VDC  
 Dielectric withstanding voltage: 500 VAC/1minute.  
 Contact resistance: 100m ohms max.  
 Mating cycle: 10000 cycles, spring is not breaking..



Pin No.	SD	MMC
P1	MMC-DAT3 SD-CD/DAT3	1P 1P
P2	MMC-CMD SD-CMD	2P 2P
P3	MMC-VSS1 SD-VSS1	3P 3P
P4	MMC-VDD SD-VDD	4P 4P
P5	MMC-CLK SD-CLK	5P 5P
P6	MMC-VSS2 SD-VSS2	6P 6P
P7	MMC-DAT0 SD-DAT0	7P 7F
P8	SD-DAT1	8P
P9	SD-DAT2	9P



CIRCUIT:	WP	GROUND	WP	GROUND	WP	GROUND
WITHOUT CARD	○	○	○	○	○	○
	○	#3	○	#3	○	#3
CARD INSERTED	○	○	○	○	○	○
	○	#3	○	#3	○	#3
CARD INSERTED	WRITE PROTECT : LOCK			WRITE PROTECT : UNLOCK		

**Ordering Information:**

SDDMF-0 T 9 XX B X 04-G

PLATING TYPE  
 T : COMPLY TO RoHS

- Contact Area Plating:
- 01 : G/F Plating
  - 03 : 3u" Gold Plating
  - 05 : 5u" Gold Plating
  - 10 : 10u" Gold Plating
  - 15 : 15u" Gold Plating
  - 30 : 30u" Gold Plating
- 0 : TRAY  
 1 : TAPE REEL

RECOMMENDED PCB LAYOUT  
 (ALL TOLERANCE ARE ±0.05)

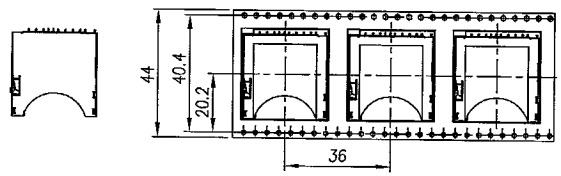
DIMENSION IN mm [Inch]	PROD. SPEC. SP0890	KINGFONT PRECISION INDUSTRIAL CO., LTD.	
TOLERANCE UNLESS OTHERWISE SPECIFIED	PKG. SPEC. 3/3	TITLE SD MEMORY CARD PUSH-PUSH CONNECTOR TYPE	CUSTOMER DRAWING
.X±0.30 X.±10'	APPROVE Garn	FILE NO.	DWG NO. SDDMF-0T9XXBX04-G
.XX±0.20 .X.±5'	CHECK Jung	SIZE A4	PROJ. SHEET 1 / 3
.XXX±0.05 .XX±1'	DRAW JSE	SCALE 1.5:1	REV F

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F	ECN2-00000181	2014.12.02	Stacy

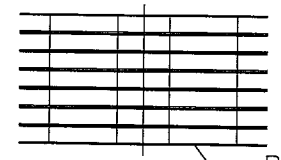
### 包裝作業規範

#### 包裝作業圖示及說明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

- 一、
- (1) 將成品一一放入REEL包裝盤內, 依同依方向放入
  - (2) 包裝時, 如圖所示
  - (3) 一個REEL包裝盤放置450個成品



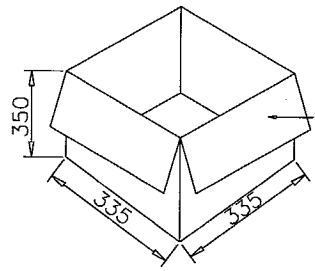
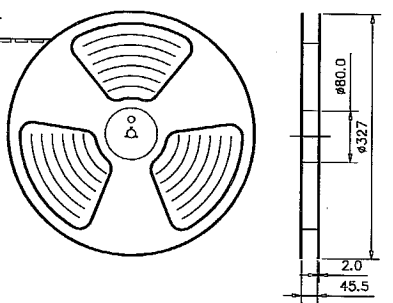
- 三、
- (1) 每箱裝6盤REEL包裝盤
  - (2) 每箱放置2700PCS的成品



REEL盤(W06-0009)

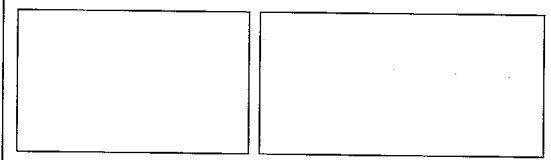
- 二、
- (1) 裝盤前把前面空10PCS產品, 然後再開始裝盤, 尾端也需空10CS產品.
  - (2) 裝滿成品的REEL包裝盤如下圖所示

PULL OUT DIRECTION



紙箱(W01-0006)

- 四、
- (1) 用TPAE將紙箱封實



備註 (REMARK)

1. 若有未裝滿之零數箱, 必須以緩衝材塞滿.



DIMENSION IN mm [Inch]		PROD. SPEC. SP0890	KINGFONT KINGFONT PRECISION INDUSTRIAL CO., LTD.	
TOLERANCE UNLESS OTHERWISE SPECIFIED		PKG. SPEC. 2/3/3	TITLE SD MEMORY CARD PUSH-PUSH CONNECTOR TYPE	CUSTOMER DRAWING
.X± 0.30	X."± 10"	APPROVE Gary	FILE NO.	DWG NO. SDDMF-0T9XXBX04-G
.XX± 0.20	.X"± 5"	CHECK Joey	SIZE A4	PROJ.  SHEET 2 / 3
.XXX± 0.05	.XX"± 1"	DRAW 30	SCALE 1.5:1	REV F

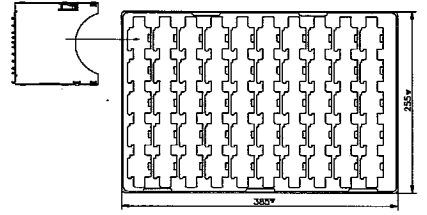
1 2 3 4 5 6 7 8

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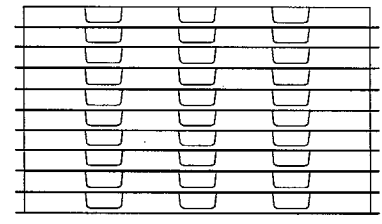
### 包裝作業規範

#### 包裝作業圖示及說明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

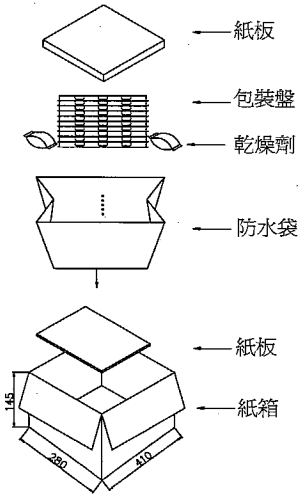
- 一、
- (1) 將成品一一放入包裝盤內,依同一方向放入。
  - (2) 包裝時,如圖所示
  - (3) 一個包裝盤放置50個成品



- 二、
- (1) 將放滿成品的包裝盤依同一方向一層層疊好。
  - (2) 如圖所示



- 三、
- (1) 每箱需放置21個包裝盤
  - (2) 最後面一個包裝盤作為上蓋,固不放置成品。
  - (3) 每箱放置1000 PCS的成品。
  - (4) 將成品放置塑膠袋內,上下面各放一包乾燥劑,包裝完成後再裝箱。



- 四、
- (1) 用TAPE將紙箱封實。

<p>ITEM NO: QTY.: PCS G.W.: KGS N.W.: KGS MEAS: cm</p>	<p>C/NO: MADE IN CHINA</p>
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備註 (REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿。



DIMENSION IN mm [Inch]		PROD. SPEC. SP0890	KINGFONT PRECISION INDUSTRIAL CO., LTD.	
TOLERANCE UNLESS OTHERWISE SPECIFIED		PKG. SPEC. 2/3/3	TITLE SD MEMORY CARD PUSH-PUSH CONNECTOR TYPE	CUSTOMER DRAWING
.X±0.30	X."±10"	APPROVE <i>Comy</i>	FILE NO.	DWG NO. SDDMF-0T9XXBX04-G
.XX±0.20	.X"±5"	CHECK <i>Stacy</i>	SIZE A4	PROJ.  SHEET 3 / 3
.XXX±0.05	.XX"±1"	DRAW <i>Stacy</i>	SCALE 1.5:1	REV F

1 2 3 4 5 6 7 8 QR-2100-043